HI1612X560R-10

UNCONTROLLED **DOCUMENT**

PHYSICAL DIMENSIONS:

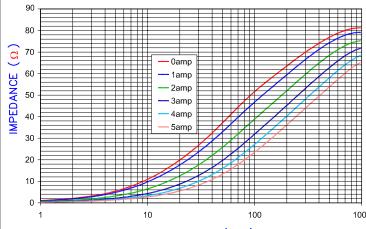
A 4.06 [.160] <u>+</u> 0.20 [.008]

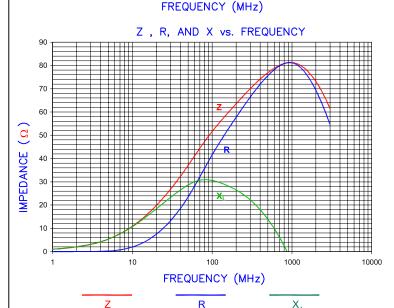
B 3.05 [.120] ± 0.20 [.008]

C 2.28 [.090] ± 0.20 [.008]

D 0.70 [.028] ± 0.25 [.010]

Z vs FREQUENCY IMPEDANCE UNDER DC BIAS





AGILENT E4991A RF Impedance/Material Analyzer

HP 16194A Test Fixture. TEST REF. 3236

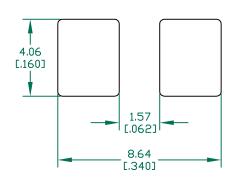


ELECTRICAL CHARACTERISTICS:			
Z @ 100MHz (Ω)		DCR $\left(\begin{array}{c}\Omega\end{array}\right)$	Rated Current
Nominal	56		
Minimum	42		
Maximum	70	0.004	10,000 mA

NOTES: UNLESS OTHERWISE SPECIFIED

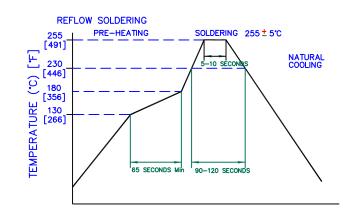
- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 13" REELS, 2,500 PCS/REEL.
- 2. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- TERMINATION FINISH IS 100% TIN.
- 4. OPERATEING TEMPERATURE TEMP: -40°C~+125°C (INCLUDING SELF-HEATING)

LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762 [.030] to this dimension.)

RECOMMENDED SOLDERING CONDITIONS





DIMENSIONS ARE IN mm [INCHES] This print is the property of Laird Tech, and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are ROJECT/PART NUMBER: HI1612X560R-10 CO-FIRE 03/21/06 JRK DATE: SHEET: 09/19/05 NTS 2 of 2 DESCRIPTION "HI1612X560R-10-G